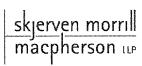


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Docket No.: M-11675 US

December 12, 2001

Box Patent Application Commissioner For Patents Washington, D. C. 20231

Inventors:

Enclosed herewith for filing is a patent application, as follows:

Title:	Compositions F	For Chemical	Mechanical Pl	anarization Of Copper
I Itio.	COMPOSITIONS	or Chomban	11100110111001 1 1	ununization of copper

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pages Specification (not including claims, abstract, and Attachments A and B)

pages Claims

Pages Attachment A & B

page Abstract Sheet of Drawings

Information Disclosure Statement

pages PTO Form 1449 listing 30 references Copy of each reference submitted

CLAIMS AS FILED

<u>For</u> Total Claims	Number <u>Filed</u> 23	-20	=	Number Extra 3	x	Rate \$18.00	=	\$ \$	Basic Fee <u>740.00</u> <u>54.00</u>
Independent Claims	2	-3	=	0	х	\$84.00	=	\$	0.00
Fee of 280.00 for the first filing of one or more multiple dependent claims per application									280.00

Please make the following charges to Deposit Account 19-2386:

Total fee for filing the patent application in the amount of \$ 1,074.00

The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

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Respectfully submitted,

K. Alison de Runtz Attorney of Record Reg. No. 37,119